Sensing for DC Link Voltage

Sensing for Module Temperature
Variant/Label Table

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
</tr>
</thead>
<tbody>
<tr>
<td>001</td>
<td>AMC1311 for DC_Link</td>
</tr>
<tr>
<td>002</td>
<td>AMC1301 for DC_Link</td>
</tr>
</tbody>
</table>

Assembly Notes:

- ZZ1: Assembly Notes
  - Note assembly notes for PCB labels only

- ZZ2: Assembly Notes
  - These assemblies are ESD sensitive, ESD precautions shall be observed.

- ZZ3: Assembly Notes
  - These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

- ZZ4: Assembly Notes
  - These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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